



This document describes the SLA7080MS series, which are unipolar 2-phase stepping motor driver ICs.

This document contains preliminary information on the products under development. If you have any questions, including information on options, please contact your nearest sales or representative office.

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1. General Description

Thank you for your long years of patronage for each series of our unipolar 2-phase stepping motor driver ICs. **The SLA7080MS series** is our latest release.

This document describes summaries of our latest products.

2. Features and Benefits

- (1) Main power supply voltages, V_{BB} : 46 V (max.), 10 to 44 V normal operating range
- (2) Logic supply voltages, V_{DD} : 3.0 to 5.5 V
- (3) Maximum output currents, $I_{O(max)}$: 2.0 A, 3.0 A
- (4) Stepping control for phase input (full-/half-stepping)
- (5) Built-in "sense resistor" detects motor current
- (6) All variants are pin-compatible for enhanced design flexibility
- (7) ZIP type 23-pin molded package (SLA package)
- (8) Self-exciting PWM current control with fixed OFF-time
- (9) Built-in synchronous rectifying circuit reduces power dissipation at PWM-OFF
- (10) Synchronous PWM chopping function prevents motor noise in the Hold mode
- (11) The Sleep mode to reduce IC input current in stand-by state
- (12) Built-in protection circuitry against motor coil opens/shorts and thermal shutdown protection
- (13) Externally-adjustable blanking times (Minimum ON-time): 3.2 μ s, 5.2 μ s

3. Part Numbers and Rated Currents

Table 3-1 shows each part number and its rated current for the SLA7080MS series.

Table 3-1. Part Numbers and Rated Currents

Part Number	Rated Current (Maximum Setting Value)
SLA7082MS	2.0 A
SLA7083MS	3.0 A

4. Specifications

Table 4-1. Absolute Maximum Ratings

Unless specifically noted, $T_A = 25\text{ }^{\circ}\text{C}$

Characteristic	Symbol	Rating	Unit	Remarks
Load (Motor Supply Voltage)	V_M	46	V	
Main Power Supply Voltage	V_{BB}	46	V	
Logic Supply Voltage	V_{DD}	6	V	Power supply to DC
		7	V	$\leq 1\text{ }\mu\text{s}$ (5% duty)
Output Current	I_O	2.0	A	SLA7082MS
		3.0	A	SLA7083MS
Logic Input Voltage	V_{IN}	$-0.3\text{ to }V_{DD} + 0.3$	V	Control current value
REF Input Voltage	V_{REF}	$-0.3\text{ to }V_{DD} + 0.3$	V	
Sense Voltage	V_{RS}	± 2	V	
Allowable Power Dissipation	P_D	4.7	W	Without heatsink
Junction Temperature	T_J	150	$^{\circ}\text{C}$	
Operating Ambient Temperature	T_A	$-20\text{ to }85$	$^{\circ}\text{C}$	
Storage Temperature	T_{stg}	$-30\text{ to }150$	$^{\circ}\text{C}$	

NOTE: Output current ratings may be limited by duty cycles, ambient temperatures, and heat sinking conditions. Do not exceed the maximum output current and maximum junction temperature (T_J) given above, under any conditions of use.

Table 4-2. Recommended Operating Conditions

Unless specifically noted, $T_A = 25\text{ }^{\circ}\text{C}$

Characteristic	Symbol	Standard Value		Unit	Remarks
		Min.	Max.		
Load (Motor Supply Voltage)	V_M		44	V	
Main Power Supply Voltage	V_{BB}	10	44	V	
Logic Supply Voltage	V_{DD}	3.0	5.5	V	Surge voltage at V_{DD} pin should be less than $\pm 0.5\text{ V}$ to avoid malfunctioning in operation
Case Temperature	T_C		90	$^{\circ}\text{C}$	Measured at Pin 12 (lead portion), without heatsink

NOTE: As the motor supply voltage, V_M , becomes higher, it also approaches the breakdown voltage of the OUTx pins (100 V min.); and breakdown will be more likely to happen. Even if one of the OUTx pins breaks down (due to surge noise or other factors), the SLA7080MS series will recognize it as abnormality (coil open) and will run appropriate protection functions. Therefore, a thorough evaluation is recommended.

Table 4-3. Electrical Characteristics

Unless specifically noted, $T_A = 25\text{ }^{\circ}\text{C}$, $V_{BB} = 24\text{ V}$, $V_{DD} = 5\text{ V}$

Characteristic	Symbol	Rating			Unit	Conditions
		Min.	Typ.	Max.		
Main Power Supply Current	I_{BB}			15	mA	Normal mode
	I_{BBS}			100	μA	Sleep mode
Logic Supply Current	I_{DD}			5	mA	
MOSFET Breakdown Voltage	V_{DSS}	100			V	$V_{BB} = 44\text{ V}$, $I_D = 1\text{ mA}$
MOS FET ON-Resistance	$R_{DS(on)}$		0.25	0.4	Ω	$I_O = 2.0\text{ A}$
			0.18	0.24		$I_O = 3.0\text{ A}$
MOS FET Body Diode Forward Voltage	V_F		0.95	1.2	V	$I_O = 2.0\text{ A}$
			0.95	2.1		$I_O = 3.0\text{ A}$
Maximum Response Frequency	f_{clk}	250			KHz	Clock duty cycle = 50%
Logic Input Voltage	V_{IL}			$0.25 \times V_{DD}$	V	
	V_{IH}	$0.75 \times V_{DD}$			V	
Logic Input Current	I_{IL}		± 1		μA	
	I_{IH}		± 1		μA	
REF Input Voltage	V_{REF}	0.04		0.4	V	2.0 A device
		0.04		0.45	V	3.0 A device
REF Input Current	I_{REFS}	2.0		V_{DD}	V	Sleep1 mode ¹⁾
SENSE Detection Voltage	V_{SENSE}	$V_{REF} - 0.03$	V_{REF}	$V_{REF} + 0.03$	V	
Sense Resistor ²⁾	R_S	0.199	0.205	0.211	Ω	2.0 A device
		0.150	0.155	0.160		3.0 A device
PWM Minimum ON-Time	$t_{on(min)}$		3.2		μs	B_SEL = Low
			5.2		μs	B_SEL = High
PWM OFF-Time	t_{off}		13		μs	
Sleep-Enable Recovery Time	t_{SE}	100			μs	
Switching Time	t_{con}		1.5		μs	Phase IN $\rightarrow$ Output ON
	t_{coff}		1.0		μs	Phase IN $\rightarrow$ Output OFF
Overcurrent Detection Voltage ³⁾	V_{OCP}	0.65	0.7	0.75	V	Motor coils shorted
Overcurrent Detection Current (V_{OCP} / R_S)	I_{OCP}		3.5		A	2.0 A device
			4.6		A	3.0 A device
Load Disconnection Undetected Time	t_{opp}		2		μs	From PWM-OFF
Overheat Protection Temperature	T_{sd}		140		$^{\circ}\text{C}$	Measured at back of device case (after heat has saturated)
FLAG Output Voltage	V_{FlagL}			1.25	V	$I_{FlagL} = 1.25\text{ mA}$
	V_{FlagH}	$V_{DD} - 1.25$			V	$I_{FlagH} = -1.25\text{ mA}$
FLAG Output Current	I_{FlagL}			1.25	mA	
	I_{FlagH}	-1.25			mA	

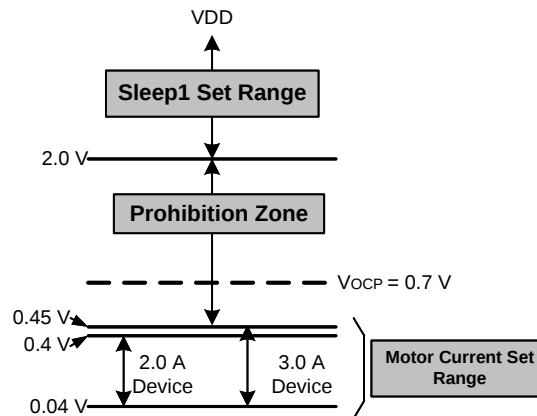
NOTE: Unless specifically noted, negative current is defined as output current flow from a specified pin.

¹⁾ In a state of: I_{BBS} , and output OFF.

²⁾ Includes approximately $5\text{ m}\Omega$ circuit resistance in addition to the resistance of the built-in resistor itself.

³⁾ Protection circuit operates when $V_{SENSE} \geq V_{OCP}$.

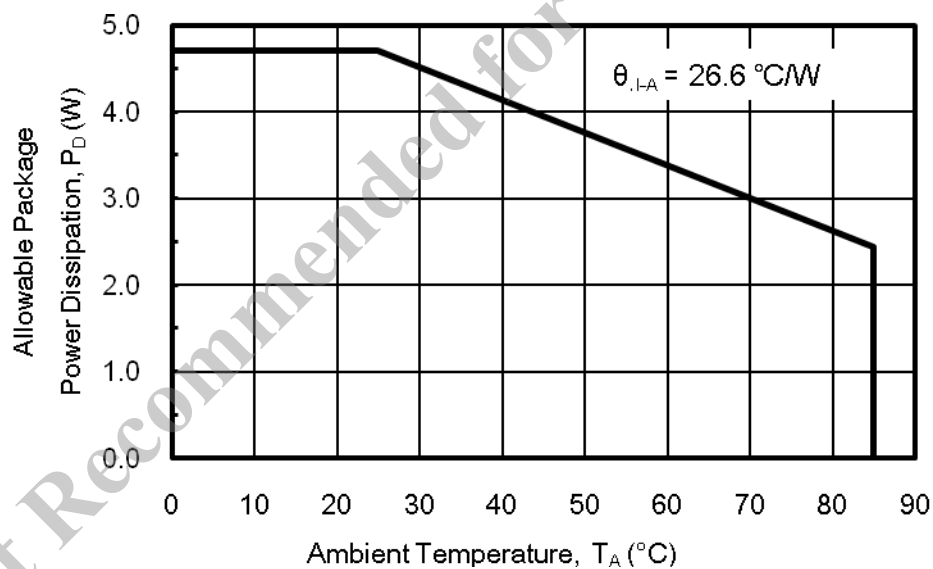
Figure 4-1. Setting Range of Reference Voltage, V_{REF}



NOTE: Extra attentions should be paid to the changeover between the motor current specification range and the Sleep1 set range. V_{OCP} falls on the “prohibition zone” threshold. If the changeover takes too long, OCP operation will start when $V_{SENSE} > V_{OCP}$.

5. Power Derating Chart

Figure 5-1. Power Derating Chart



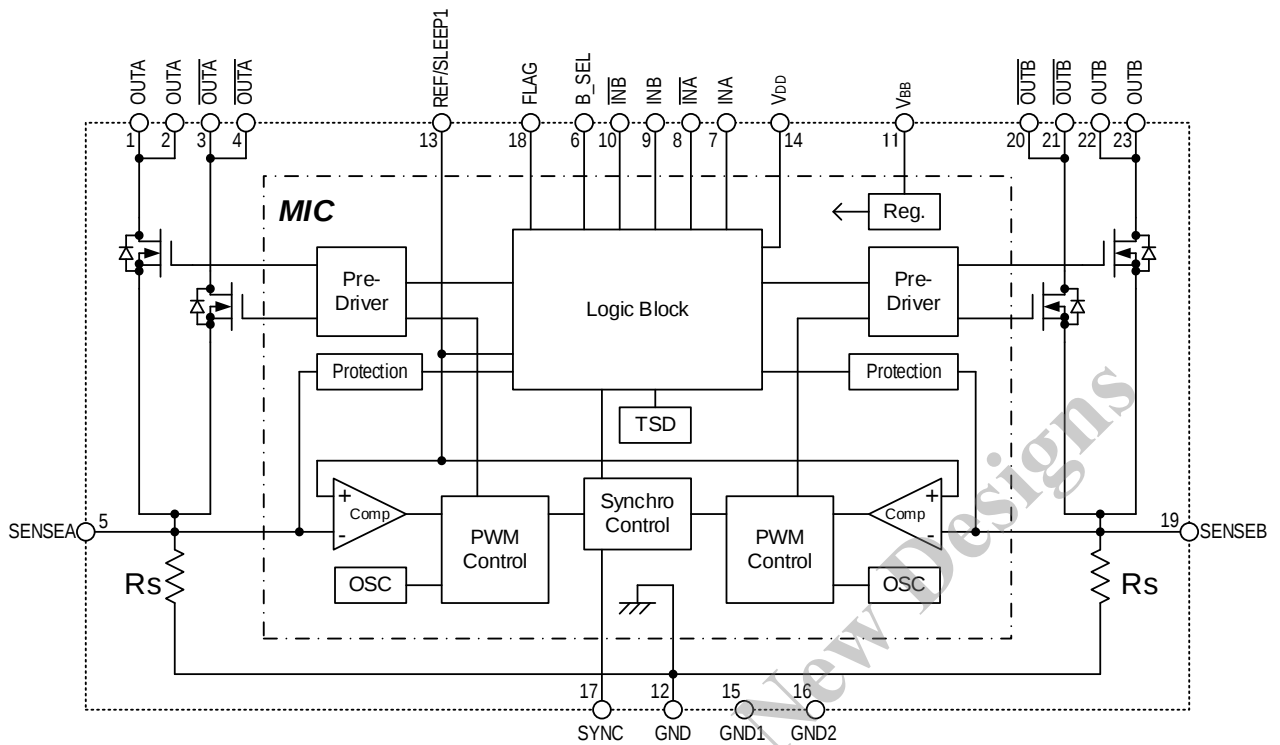
[illegible]

- Dimensions in millimeters
- Pin material: Cu
- Pin plating: Solder plating (Pb-free)
- Branding codes:

- a** Part number: *SLA708xMS*
- The lowercase letter *x* represents a number of either of 2 or 3, according to rated current. See also Table 3-1.
- b** Lot number: *YMDD*
- *Y* is the last digit of the year of manufacture
 - *M* is the month of the year (1 to 9, O, N, or D)
 - *DD* is the day of the month (01 to 31)

7. Functional Block Diagram and Pin Assignment

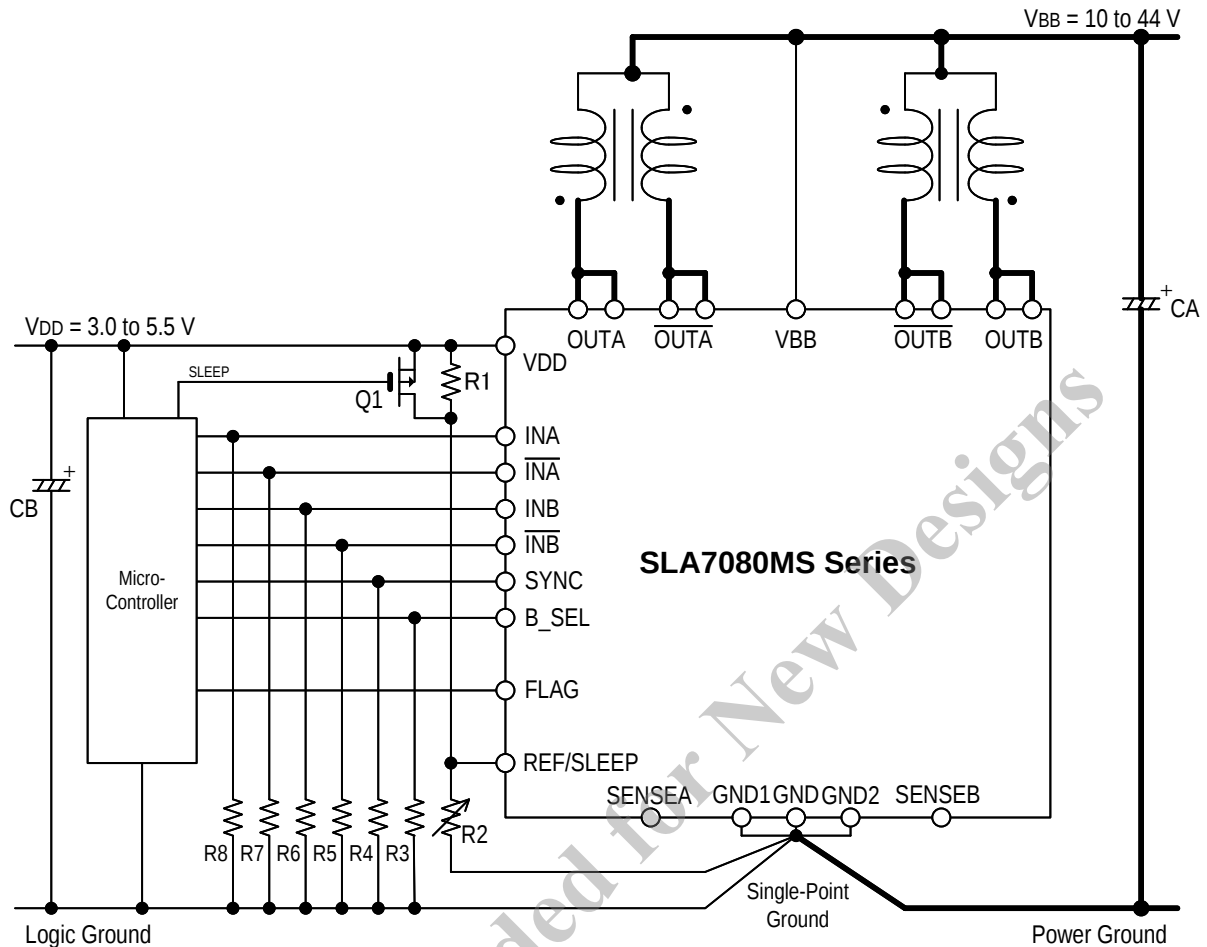
Figure 7-1. SLA7080 Series Functional Block Diagram



Pin No.	Symbol	Function
1, 2	OUTA	Phase A output
3, 4	$\overline{\text{OUTA}}$	Phase A output
5	SENSEA	Phase A current sensing
6	B_SEL	Blanking time switching input
7	INA	Switching input for Phase A
8	$\overline{\text{INA}}$	
9	INB	
10	INB	Switching input for Phase B
11	V _{BB}	
12	GND	
13	REF/SLEEP	Input for control current / Sleep setting
14	V _{DD}	Logic power supply
15	GND1	Ground 1
16	GND2	Ground 2
17	SYNC	PWM control switch input
18	FLAG	Output from protection circuit monitor
19	SENSEB	Phase B current sensing
20, 21	$\overline{\text{OUTB}}$	Phase B output
22, 23	OUTB	Phase B output

8. Application Example

Figure 8-1. Application Example



Constants, for reference use only:

R1 = 10 k Ω

R2 = 1 k Ω (VR)

R3 to R8 = 1 to 10 k Ω

(Not required if input state does not reach indefinite.)

CA = 100 μ F / 50 V

CB = 10 μ F / 10 V

C1 = 0.1 μ F

C2 = 0.1 μ F

NOTES:

- Take precautions to avoid noise on the V_{DD} line; noise levels greater than 0.5 V on the V_{DD} line may cause device malfunction. Noise can be reduced by separating the logic ground and the power ground on a PCB from the GND pin (Pin 12).
- Unused logic input pins (INA, $\overline{\text{INA}}$, INB, $\overline{\text{INB}}$, B_SEL, and SYNC) **must be pulled up or down to VDD or ground**. If those unused pins are left open, the device may malfunction or break down.
- Unused logic output pin (FLAG) **must be kept open**.

9. Truth Tables

(1) Dual Phase Inputs and Outputs

The SLA7080MS series allows dual phase operations. The phase-switching logic is shown in Table 9-1.

Table 9-1. Truth Table for Phase-Switching Input Pins

Phase A	INA (Pin 7)	$\overline{\text{INA}}$ (Pin 8)	OUTA (Pins 1, 2)	$\overline{\text{OUTA}}$ (Pins 3,4)
	Low	Low	OFF	OFF
	High	Low	ON	OFF
	Low	High	OFF	ON
	High	High	OFF	OFF
Phase B	INB (Pin 9)	$\overline{\text{INB}}$ (Pin 10)	OUTB (Pins 22, 23)	$\overline{\text{OUTB}}$ (Pins 20, 21)
	Low	Low	OFF	OFF
	High	Low	ON	OFF
	Low	High	OFF	ON
	High	High	OFF	OFF

NOTE: OUTx indicates power MOSFET drain state (does not indicate PWM operation).

(2) Logic Input Pins

Table 9-2 explains the logic for input pins other than the phase-switching input logic described above.

Table 9-2. Truth Table for Logic Input Pins

Pin Name	Low Level	High Level
SYNC	Non-sync PWM control	Synchronous PWM control
B_SEL	Blanking time: 3.2 μs	Blanking time: 5.2 μs

(3) Logic Output Pin (FLAG)

Table 9-3 shows the logic for monitor output.

Table 9-3. Truth Table for Monitor Output Pin

Pin Name	Low Level	High Level
FLAG	Normal operation	Protection circuit operation

NOTE: The output turns off at the point where the protection circuit starts operating. To release the protection state, cycle the logic supply voltage, V_{DD} .

Logic Input Pins

The low pass filter (LPF) incorporated with the logic input pins (INA, $\overline{\text{INA}}$, INB, $\overline{\text{INB}}$, SYNC, and B_SEL) improves noise rejection.

The logic inputs are CMOS input compatible; therefore, they are in a high impedance state. **Note that the IC should be used at a fixed input level, either low or high.**

If there is a possibility that signals from the microcontroller are in high impedance, add a pull-up/-down resistor. Since outputs from the logic input pins, which function as output ON/OFF controllers, may result in abnormal oscillation, leading to MOSFET breakdown as the worst-case scenario.

10. Individual Circuit Descriptions

(1) Monolithic IC (MIC)

- Logic Block

A circuit block that operates with the logic power supply, V_{DD} , and transmits signals to each circuit in accordance with logic input signals.

- PWM Control

Circuits that allow self-excitation PWM current controlling with a fixed OFF-time are used in this series. Each built-in oscillator (OSC) determines an OFF-time and a blanking time for proper PWM operation. For more detailed functional descriptions, see Section 11.

- Synchronous Control

A synchronous chopping circuit that prevents occasional motor noise during a hold state which normally results from the asynchronous PWM operation of both motor phases. When the SYNC input pin is set to logic high, the circuit sends a timing signal that simultaneously turns off the chopping of phases A and B.

This function adopts the same operation mechanism applied to the SLA7070M series. The use of the synchronous control during normal stepping is not recommended, because it produces less motor torque or may cause motor vibration due to staircase current.

- Regulator Circuit

An integrated regulator circuit is used for powering the output MOSFET gate drive circuit (pre-driver) and other internal linear circuits.

- Protection Circuit

Built-in protection circuits against motor coil opens or shorts are provided. This protection is activated by sensing the voltage across internal sense resistors, R_s . Therefore, an overcurrent condition cannot be detected which results from the OUTx pins or SENSEx pins, or both, shorting to GND. The protection against motor coil opens is available only during PWM operation; therefore, it does not work at constant voltage driving, when the motor is rotating at a high speed.

The operation of the protection circuit disables all outputs. To come out of the Protection mode, cycle the logic supply, V_{DD} . For more details, see the next section.

- TSD Circuit

A TSD circuit that protects a driver by shifting an output to the Disable mode is incorporated. When the temperature of the product control IC (MIC) rises and becomes higher than its threshold, the circuit starts operating.

To reset the function, perform the same steps as described in the Protection Circuit description.

(2) Output MOSFET Chip

The type of MOSFET chips to be mounted varies according to which of the two different output current ratings has been selected. For specifications, see Table 4-3.

Rated Current (A)	Resistance (Ω Typ.)
2.0	0.25
3.0	0.18

NOTE: Each resistance shown above includes approximately 5 m Ω circuit resistance in addition to the resistance of the built-in resistor itself.

(3) Sense Resistor

Sense resistors are incorporated in this series to detect motor current. The resistance of these varies according to which of the two different output current ratings has been selected. For specifications, see Table 4-3.

Rated Current (A)	Resistance (Ω Typ.)
2.0	0.205
3.0	0.155

NOTE: Each resistance shown above includes approximately 5 m Ω circuit resistance in addition to the resistance of the built-in resistor itself.

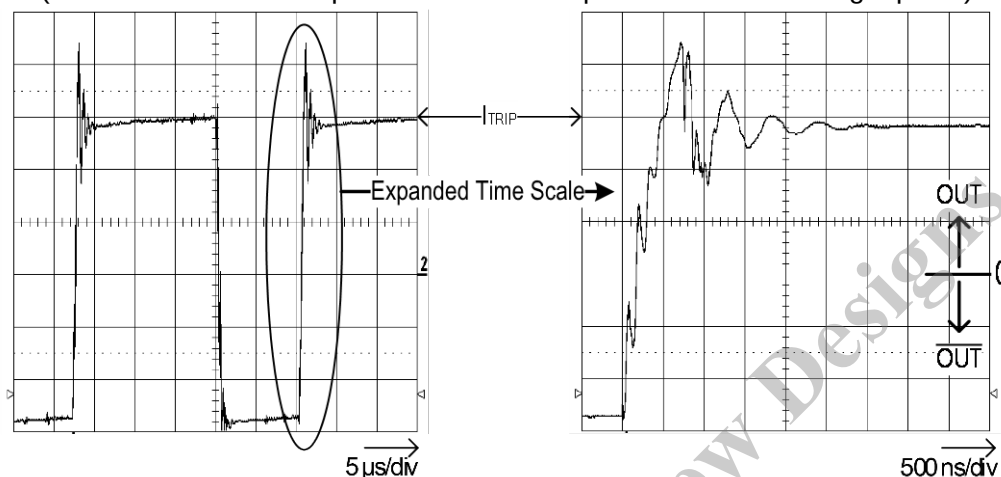
11. Functional Descriptions

(1) PWM Current Control

[1] Blanking Time

An actual operating waveform on the SENSEx pin when driving a motor are shown in Figure 11-1.

Figure 11-1. Operating Waveforms on SENSEx Pin during PWM Chopping
(Circled area of the left panel is shown in expanded scale in the right panel)



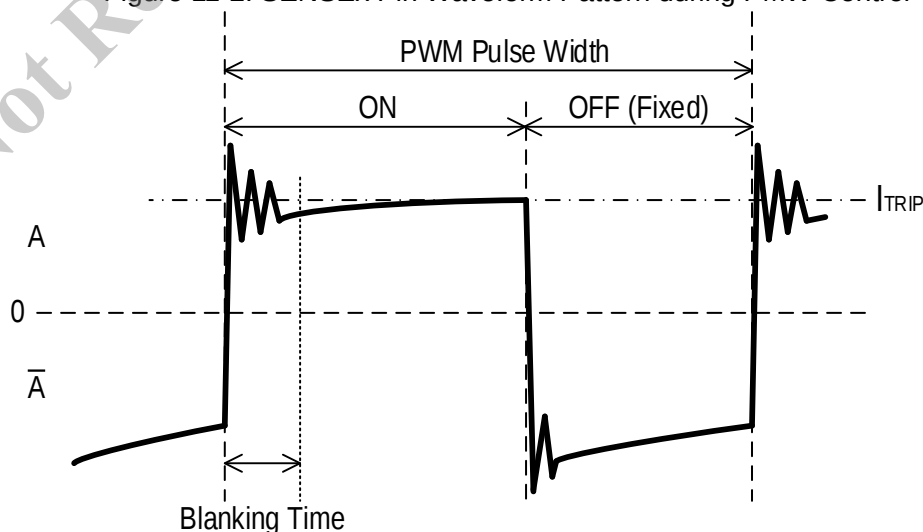
Immediately after a PWM turns off, ringing (or spike) noise on the SENSEx pin is observed for a period of a few microseconds. Ringing noise can be generated by various causes, such as capacitance between motor coils or inappropriate motor wiring.

Each pair of outputs is controlled by a fixed OFF-time PWM current-control circuit that limits the load current to a target value, I_{TRIP} . Initially, an output is enabled and then currents flow through the motor winding and the current sense resistors.

When the voltage across the current sense resistors equals the DAC output voltage, V_{TRIP} , the current sense comparator resets a PWM latch. This turns off the driver for the fixed OFF-time, during which the load inductance causes the current to recirculate for the OFF-time period. Therefore, if the ringing noise on the current sense resistor(s) equals and surpasses V_{TRIP} , the PWM turns off (i.e., a hunting phenomenon).

To prevent this phenomenon, a blanking time is set to override signals from the current sense comparator for a certain period immediately after the PWM turns on (Figure 11-2).

Figure 11-2. SENSEx Pin Waveform Pattern during PMW Control



[2] Blanking Time and Hunting Phenomenon

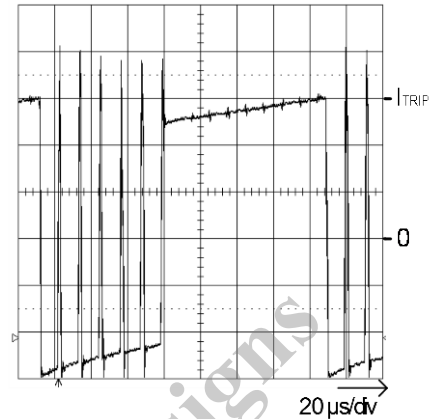
Although current control can be improved by shortening a blanking time, the degree of margin to a ringing noise decreases simultaneously.

For this reason, when a motor is driven by the device, a hunting phenomenon may occur. Figure 11-3 shows an example of the waveform pattern when the phenomenon occurs.

In order to overcome this problem, the SLA7080MS series is designed to have the B_SEL pin, allowing the dynamic selection of blanking time duration.

In the event that the seeking behavior occurs with a shorter blanking time of 3.2 μs , it may be eased by selecting a longer blanking time of 5.2 μs .

Figure 11-3. Example of SENSEx Pin Waveform during Hunting Phenomenon



[3] Blanking Time Difference

Table 11-1 shows characteristic differences between two blanking times, shorter and longer blanking periods.

This comparison is based on the case where drive conditions, such as a motor, motor power supply voltage, REF input voltage, and circuit constant were kept the same while only the indicated parameters were changed.

Table 11-1. Characteristic Comparison of Difference in Blanking Time

Parameter	Better Performance	
	Short	Long
Internal blanking time		
Minimum PWM ON-time	Small ←	
Ringing noise suppression		→ Large
Minimum coil current	Small ←	

The following are the brief descriptions of the parameters in Table 11-1:

• Minimum PWM ON-time, $t_{ON(min)}$

This series has a blanking time that is effectively selected and fixed by the PWM control. Therefore, even if an application attempts to shorten its ON-time for limiting currents, it would not go below the fixed blanking time. Minimum PWM ON-time refers to the time when an output is on during this blanking time period, that is, when an output MOSFET is actually turned on. In other words, a blanking time determines a minimum ON-time ("Small" in Table 11-1).

• Minimum Coil Current

This refers to the coil current when the PWM control is performed during a minimum PWM ON-time. In other words, the device with a shorter blanking time can reduce more coil current.

[4] PWM OFF-time

PWM OFF-time for the SLA7080MS series is controlled at a fixed time generated by the corresponding internal oscillator.

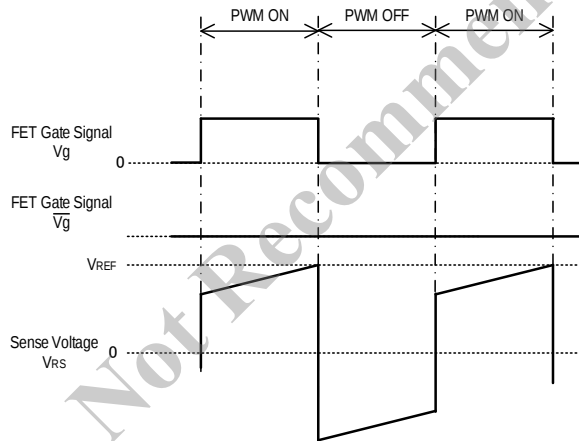
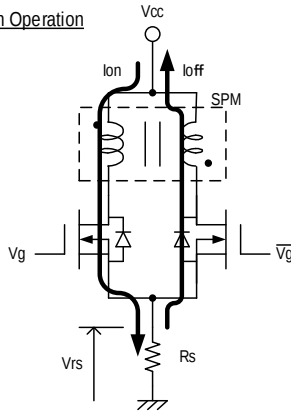
In addition, the SLA7080MS series provides a function that decreases power losses occurring when the PWM turns off. This function dissipates the back EMF stored in the motor coil at MOSFET turn-on, as well as at PWM turn-on (synchronous rectification operation).

Figure 11-4 explains differences between two back EMF generation mechanisms. Whereas the older version of our product series only performs ON/OFF operations using a MOSFET on the PWM-ON side, the SLA7080MS series can perform ON/OFF operations using a MOSFET on the PWM-OFF side.

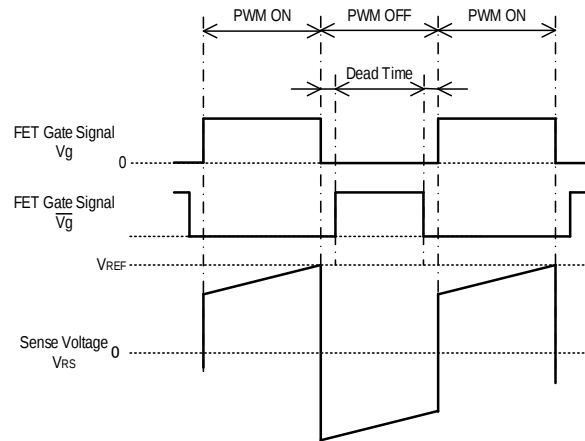
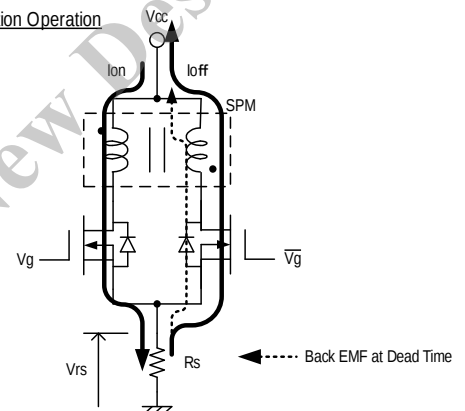
To prevent simultaneous switching of the output MOSFETs at the synchronous rectification operation, the IC has a dead time of approximately 0.5 μ s. During the dead time, the back EMF flows through the body diodes of the MOSFETs.

Figure 11-4. Difference in Back EMF Generation

Normal Rectification Operation



Synchronous Rectification Operation



Back EMF flows through the body diode of MOSFET during dead time.

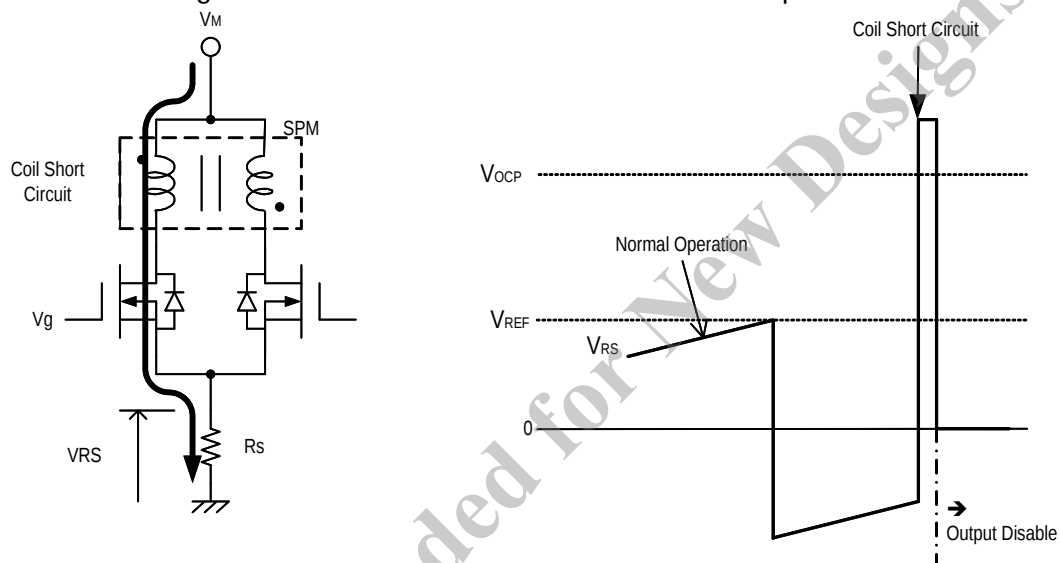
(2) Protection Functions

The SLA7080MS series includes a motor coil short protection circuit, a motor coil open protection circuit, and an overheat protection circuit. Detailed explanations of each protection circuit are provided below.

[1] Motor Coil Short Protection (Load Short) Circuit

This protection circuit, embedded in the SLA7080MS series, begins to operate when the device detects an increase in the sense resistor voltage level, V_{RS} . The voltage at which the motor coil short-circuit protection circuit starts its operation, V_{OCP} , is set to approximately 0.7 V. Outputs are disabled at the time the protection circuit starts, **where V_{RS} exceeds V_{OCP} .**

Figure 11-5. Motor Coil Short Protection Circuit Operation



NOTES:

- Overcurrent that flows without passing the sense resistor is undetectable.
- To recover the circuit after the protection operates, V_{DD} must be cycled and started up again.

[2] Motor Coil Open Protection Circuit (*Patent acquired*)

Driver destruction can occur when one output pin (motor coil) is disconnected in unipolar drive operation. This is because a MOSFET connected after disconnection will be in an avalanche breakdown state, where very high energy is added with back EMF when PWM is off. With the avalanche state, an output cancels the energy stored in the motor coil where the resisting pressure between the drain and source of the MOSFET is reached (i.e., the condition in which the breakdown occurred).

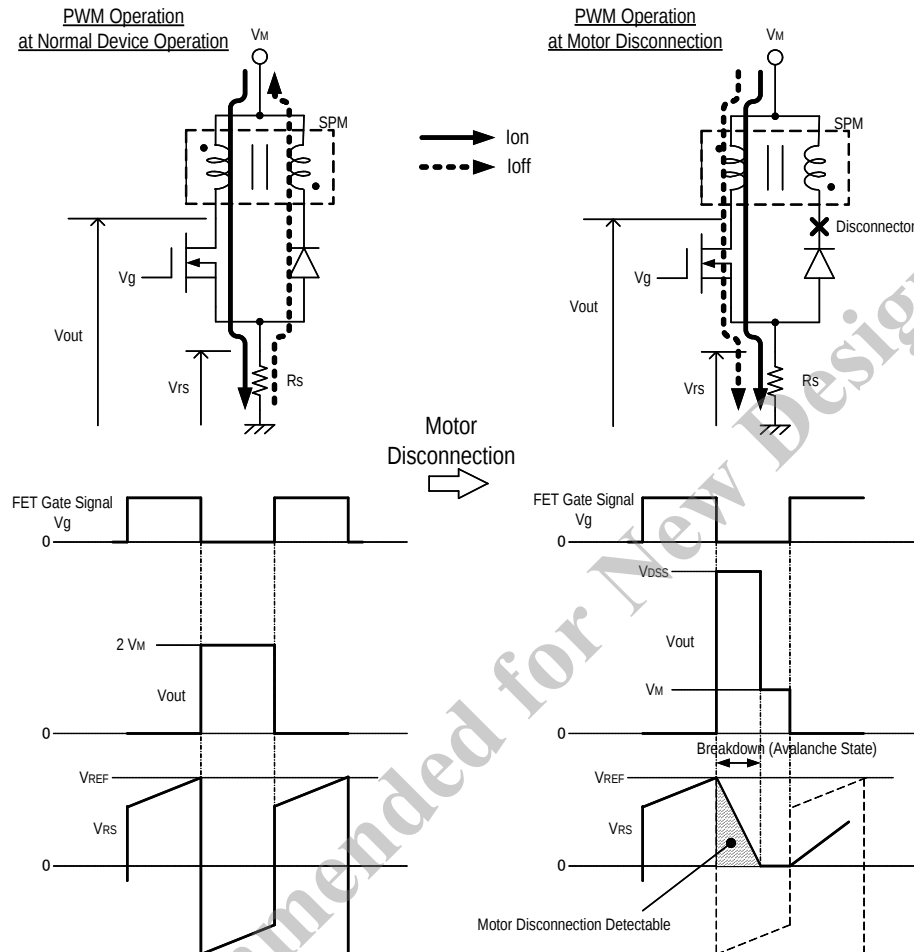
Although MOSFETs with a certain amount of an avalanche energy tolerance rating are used in the SLA7080MS series, the avalanche energy tolerance falls as a temperature increases.

Because high energy is added repeatedly whenever PWM operation disconnects the MOSFET, the temperature of the MOSFET rises; and when the applied energy exceeds the tolerance, the driver will be destroyed. Therefore, a circuit which detects this avalanche state and protects the driver is added in the SLA7080MS series.

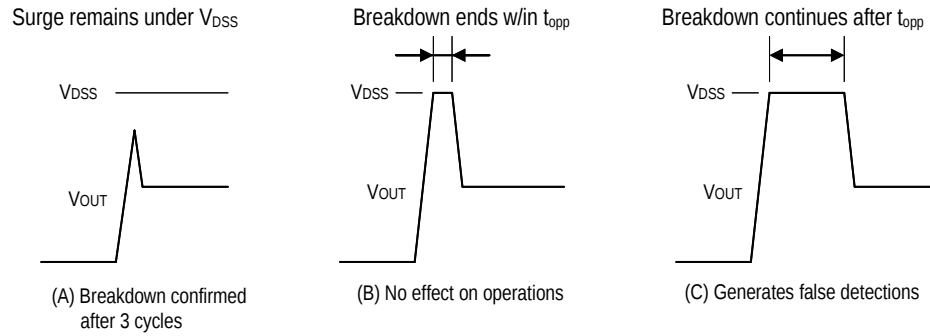
As explained above, when the motor coil is disconnected, accumulated voltage in the MOSFET causes a reverse current to flow during a PWM OFF-time. For this reason, V_{RS} that is negative during a PWM OFF-time in a normal operation becomes positive when the motor coil is disconnected. Thus, the disconnected motor is detectable by sensing that V_{RS} in the PWM OFF-time is positive.

In order to avoid detection malfunctions, the SLA7080MS series actuates a dedicated protection function, the motor coil open protection circuit, when the motor disconnection state is detected three times continuously (see Figure 11-6).

Figure 11-6. Coil Open Protection Operation



NOTE: In addition to requiring three breakdown cycles to confirm the open circuit condition, the SLA7080MS series provides a fixed delay, an overload disconnection undetected time (t_{opp}), before the protection is activated. This is to avoid false detections, which can be occurred by surge noise after PWM turn-off, causing an unwanted operation of the function even when the load is not actually disconnected. The figure below describes alternative t_{opp} scenarios. If a total period of breakdown time exceeds t_{opp} , the device shuts down the output. If this is the case, check the motor and wiring layout to reduce surge noise. Shortening the breakdown time will allow the protection circuit to function properly. (Variation among device variants and applications should be taken into consideration.) When there is no actual breakdown, normal operations will continue. One possible solution is adding a capacitor between the OUTx and GND pins, which could damp the surge noise sufficiently.



[3] Overheat Protection Circuit

When a product temperature rises and exceeds T_{tsd} , this protection circuit starts operating and sets all outputs to be disabled.

NOTE: This product series has multichip composition (one IC for control, four MOSFETs, and two chip resistors). Although main heat sources are the MOSFETs and chip resistors, the location which actually detects temperature is the control IC (MIC). Separated from these main heat sources, the control IC cannot detect a rapid temperature change. Accordingly, perform worst-case thermal evaluations, in which junction temperatures must not exceed a guaranteed value of 150 °C, in your application design phase.

12. Application Information

(1) Motor Current Ratio Setting

The motor current, I_o , for the SLA7080MS series is determined by the values chosen for the external components, $R1$ and $R2$, and the current sense resistors, R_s , in the case of the sample application circuit shown in Figure 8-1. The formula to calculate I_o is shown below:

$$I_o = \frac{R2}{\underline{\underline{R1 + R2}}} \times \underline{\underline{V_{DD}}} / R_s. \quad (1)$$

The double-underlined term represents the reference voltage, V_{REF} .

If V_{REF} is set below 0.04 V, the accuracy of I_o setting is more likely to be degraded due to the variation between individual devices and/or the impedance of application trace layout.

(2) Lower Limit of Control Current

The SLA7080MS series uses a self-oscillating PWM current-control topology in which the OFF-time is fixed. As energy stored in motor coil is eliminated within the fixed PWM OFF-time, a coil current flows intermittently, as shown in Figure 12-1. Thus, average current decreases as well as motor torque decreases. The point at which current starts flowing to the coil is considered as the lower limit of the control current, $I_{O(min)}$, where I_{OUT} is the target current level.

The lower limit of control current differs by application conditions of the motor or other factors, but it can be calculated from the following formula:

$$I_{O(min)} = \frac{V_M}{R} \left(\frac{1}{\exp\left(-t_{OFF}/t_C\right)} - 1 \right), \quad \text{with } t_C = \frac{L_m}{R}, \text{ and} \quad (2)$$

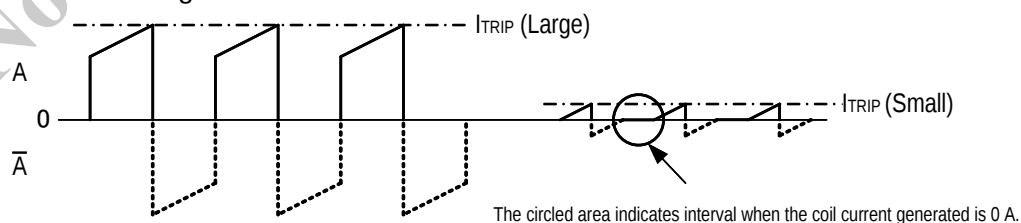
$$R = R_m + R_{DS(on)} + R_s.$$

Where:

V_M is the motor supply voltage,
 $R_{DS(on)}$ is the MOS FET on-resistance,
 R_m is the motor winding resistance,
 L_m is the motor winding inductance,
 t_{OFF} is the PWM OFF-time, and
 R_s is the current sense resistor.

Even if the control current value is set at less than its lower limit, there is no setting at which the IC fails to operate. However, the control current will worsen against its target current.

Figure 12-1. Model Waveform of Control Current Lower Limit



(3) Avalanche Energy

In the unipolar topology of the SLA7080MS series, a surge voltage (ringing noise) that exceeds the MOSFET capacity to withstand might be applied to the IC. To prevent damage, the SLA7080MS series is designed with built-in MOSFETs having sufficient avalanche resistance to withstand this surge voltage. Therefore, even if surge voltages occur, users will be able to use the IC without any problems.

However, in case the motor harness used is too long or the IC is used above its rated current or voltage, there is a possibility that an avalanche energy could be applied that exceeds Sanken design expectations. Thus, users must test the avalanche energy applied to the IC under actual application conditions.

The following procedure can be used to check the avalanche energy in an application. Figure 12-2 and Figure 12-3 show test points and waveform characteristics resultant, respectively.

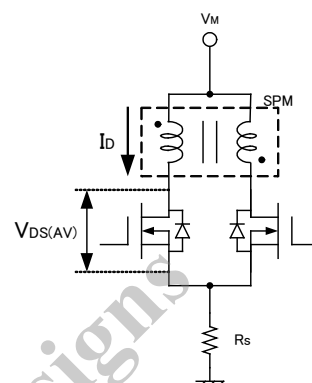


Figure 12-2. Test Points

From the waveform test result shown in Figure 12-3:

$$\begin{aligned} V_{DS(AV)} &= 140 \text{ V,} \\ I_D &= 1 \text{ A, and} \\ t &= 0.5 \text{ } \mu\text{s.} \end{aligned}$$

The avalanche energy, E_{AV} , then can be calculated using the following formula:

$$\begin{aligned} E_{AV} &\approx V_{DS(AV)} \times 1/2 \times I_D \times t \\ &= 140 \text{ (V)} \times 1/2 \times 1 \text{ (A)} \times 0.5 \times 10^{-6} \text{ (}\mu\text{s)} \\ &= 0.035 \text{ (mJ).} \end{aligned} \quad (3)$$

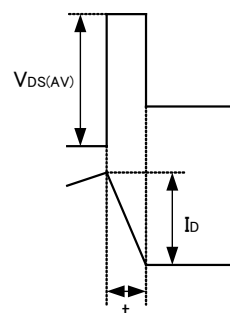
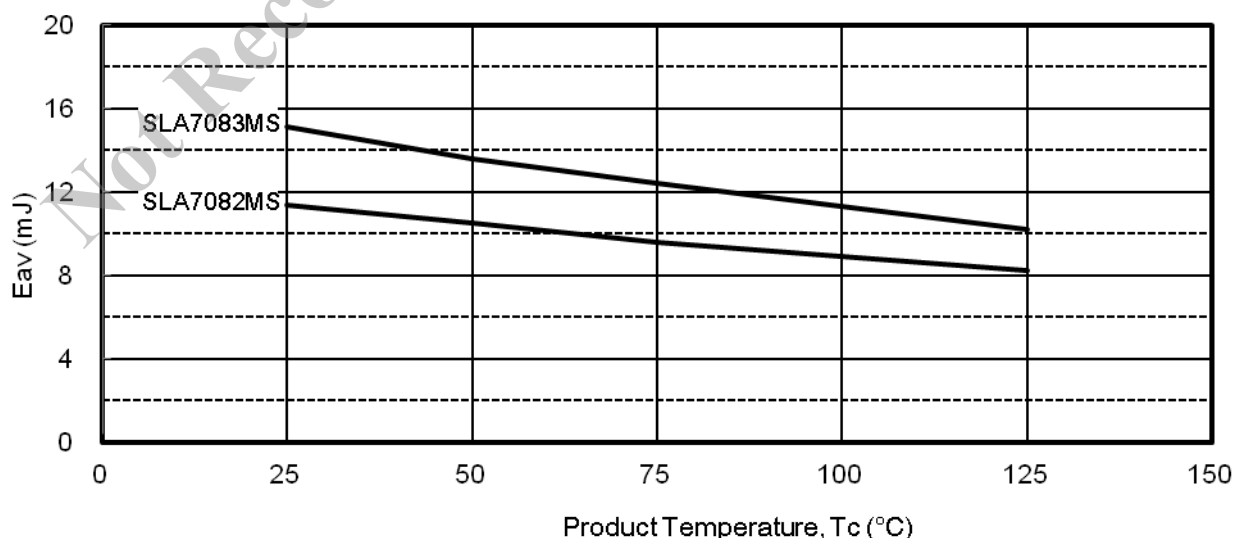


Figure 12-3. Waveform at Avalanche Breakdown

By comparing the calculated E_{AV} values with the graph shown in Figure 12-4, the application can be evaluated if it is safe for the IC by being within the avalanche energy-tolerated dose range of the MOFSETs.

Figure 12-4. Iterated Avalanche Energy Tolerated Level, E_{AV}



(4) ON/OFF Sequence of Power Supply (V_{BB} and V_{DD})

There is no restriction for the ON/OFF sequences of the main power supply, V_{BB} , and the logic supply, V_{DD} .

(5) Motor Supply Voltage (V_M) and Main Power Supply Voltage (V_{BB})

Because the SLA7080MS series has a structure that separates the control IC (MIC) and the power MOSFETs as shown in Figure 7-1, the motor supply and main power supply are electrically separated. Therefore, it is possible to drive the IC with using different power supplies and different voltages for the motor supply and the main power supply.

(6) Internal Logic Circuits

a. Chopping Synchronous Circuit

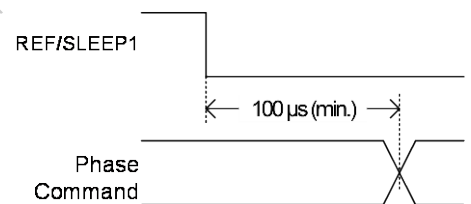
The SLA7080MS series has a chopping synchronous function to protect from abnormal noises that may occasionally occur during the motor Hold mode. This function can be operated by setting the SYNC pin at high level. However, if this function is used during motor rotation, control current does not stabilize; and that may result in reduced motor torque and/or increased vibration.

b. Output Disable Circuit (Sleep)

The SLA7080MS series can be set into the Sleep mode, in which the motor is in a free state. To enable this function, set the REF pin at more than 2 V. In the Sleep mode, the IC stops the main power supply and reduces circuit current.

When awaking to the normal operation mode (motor rotation) from the Sleep mode, set an appropriate delay time, i.e., a time period from cancellation of the Sleep mode to the next motor phase input command. In doing so, consider not only a rise time for the IC, but also a rise time for the motor excitation current (Figure 12-5).

Figure 12-5. Timing Delay between Disable Mode Cancellation and the Next Phase Input



c. REF/SLEEP1 Pin

The REF pin provides access to the following functions:

[1] Reference voltage setting for output current level setting:

Low level ($V_{REF} \leq 0.3$ to 0.45 V, depends on rated currents)

[2] Output Enable-Disable control input:

High level ($V_{REF} \geq 2.0$ V)

These functions are further described in Section 9, and in the discussion of output disabling, above. Moreover, the threshold voltage to switch the output enable-disable signals is set to approximately 1.75 V.

To control the REF voltage, pay attention to the following points:

Range A – Control current value varies in accordance with V_{REF} , not only within the range specified in [1], but also within the range from [1] to the threshold voltage (typically 1.75 V). Therefore, power dissipation in the IC and the sense resistors must be given extra consideration. In addition, note that OCP operation may start depending on the reference voltage splitting ratio.

Range B – In this range, the voltage that switches output enable and disable exists. At enable, the same cautions apply as in **Range A**. For some cases, there are possibilities that an output status will become unstable as a result of iterations between enable and disable states.

d. Logic Pins

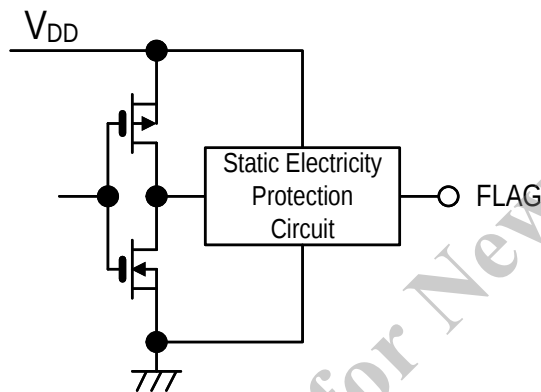
- Logic Input Pins (INA, $\overline{\text{INA}}$, INB, $\overline{\text{INB}}$, SYNC, and B_SEL)

When a logic input pin (INA, $\overline{\text{INA}}$, INB, $\overline{\text{INB}}$, SYNC, or B_SEL) is not used, the pin must be tied to VDD or GND. Do not leave any of these pins floating, because there is possibility of undefined effects on IC performance if they are left open.

- Monitor Output Pin (FLAG)

The FLAG pin is designed as a monitor output. Moreover, the IC consists of **an inverter output** configuration, as shown in Figure 12-6. Therefore, let the pin open when it is not used.

Figure 12-6. FLAG Pin General Internal Circuit Layout



13. Thermal Design Information

It is not practical to calculate the power dissipation of the SLA7080MS series accurately, because that would require factors that are variable during operation, such as time periods and excitation modes during motor rotation, input frequencies and sequences, and so forth.

Given this situation, it is preferable to perform approximate calculations at worst conditions. The following is a simplified formula for the calculation of power dissipation using extracted minimum necessary parameters:

$$P = I^2 \times (R_{DS(on)} + R_s) \times 2,$$

where:

P is the power dissipation in the IC,

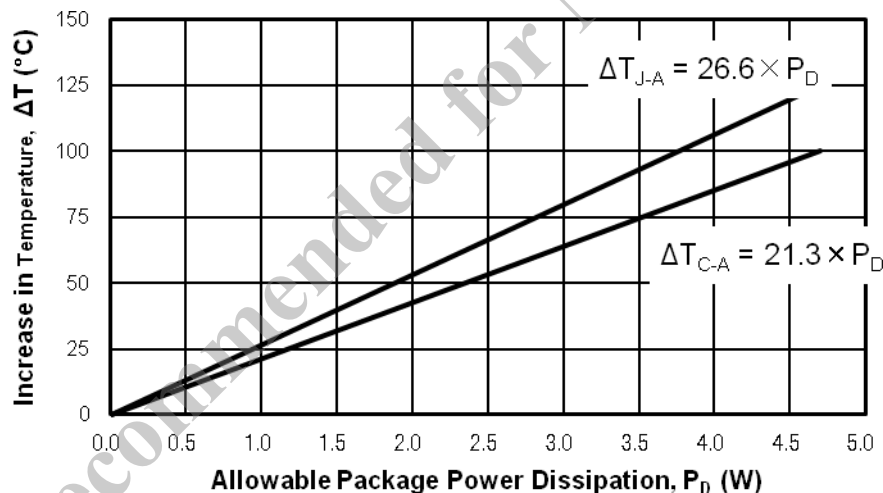
I is the operation current ($\approx I_o$),

$R_{DS(on)}$ is the on-resistance of the output MOSFET, and

R_s is the current sense resistance.

Based on the power dissipation in the IC calculated using the above formula, the expected increase in operating junction temperature, ΔT_J , of the IC can be estimated using Figure 13-1. This result should be added to the worst-case ambient temperature when operating, $T_{A(max)}$. Based on the calculation, there is no problem unless $T_{A(max)} + \Delta T_J > 150^\circ\text{C}$. However, final confirmation should be made by measuring the IC temperature during operation and then verifying power dissipation and junction temperature in the corresponding graph in Figure 13-1.

Figure 13-1. Temperature Increase



When the IC is used with a heatsink mounted, product package thermal resistance, θ_{J-A} , is a variable used in calculating ΔT_{J-A} . The value of θ_{J-A} is calculated from the following formula:

$$\theta_{J-A} \approx \theta_{J-C} + \theta_{FIN} = (\theta_{J-A} - \theta_{C-A}) + \theta_{FIN},$$

where θ_{FIN} is the thermal resistance of the heatsink. Then, ΔT_{J-A} can be calculated with using the value of θ_{J-A} .

The following procedure should be used to measure product temperature and to estimate junction temperature in actual operation.

First, measure a temperature rise in the center of backside of mold resin used for the device (ΔT_{C-A}).

Second, estimate power dissipation (P) and junction temperature (T_J) from the temperature rise with reference to Figure 13-1, the Temperature Increase graph. At this point, the device temperature rise (ΔT_{C-A}) and the junction temperature rise (T_J) become almost equivalent in the following formula:

$$\Delta T_J \approx \Delta T_{C-A} + P \times \theta_{J-C}.$$

CAUTION

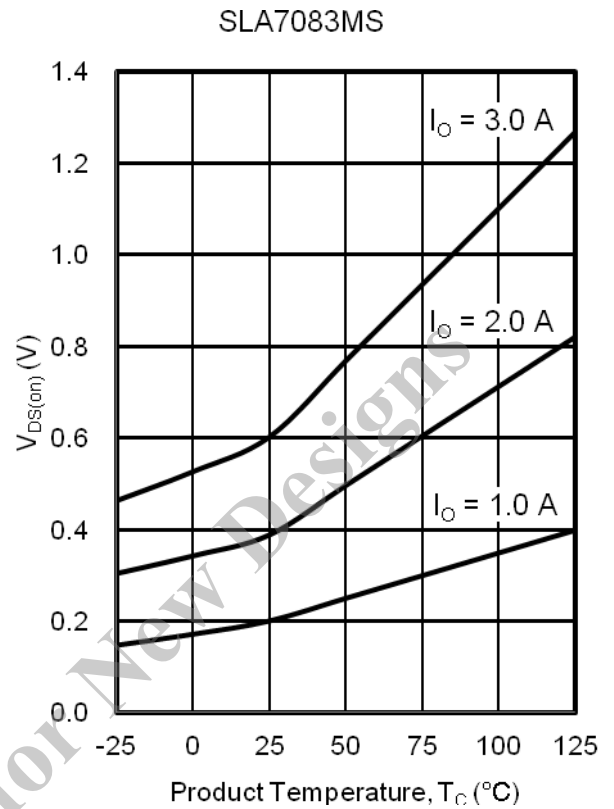
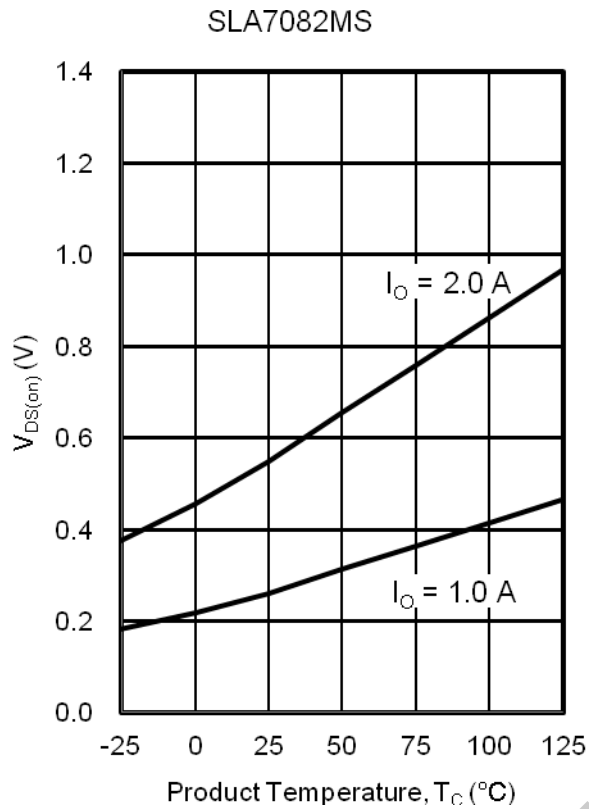
The SLA7080MS series is designed as a multichip, consisting of four separate power elements (MOSFETs), one control IC (MIC), and two sense resistors. Moreover, because the control IC cannot accurately detect the temperature of the built-in power elements, which are the primary sources of heat, the SLA7080MS series does not provide a protection function against overheating. For thermal protection, users must conduct sufficient thermal evaluations to ensure that the junction temperature of the IC does not exceed a guaranteed level of 150 °C.

This thermal design information is provided for preliminary design estimations only. Before operating the IC in an application, users must experimentally determine its actual thermal performance (the case temperature of Pin 12). The maximum recommended case temperatures (Pin 12) for the IC are:

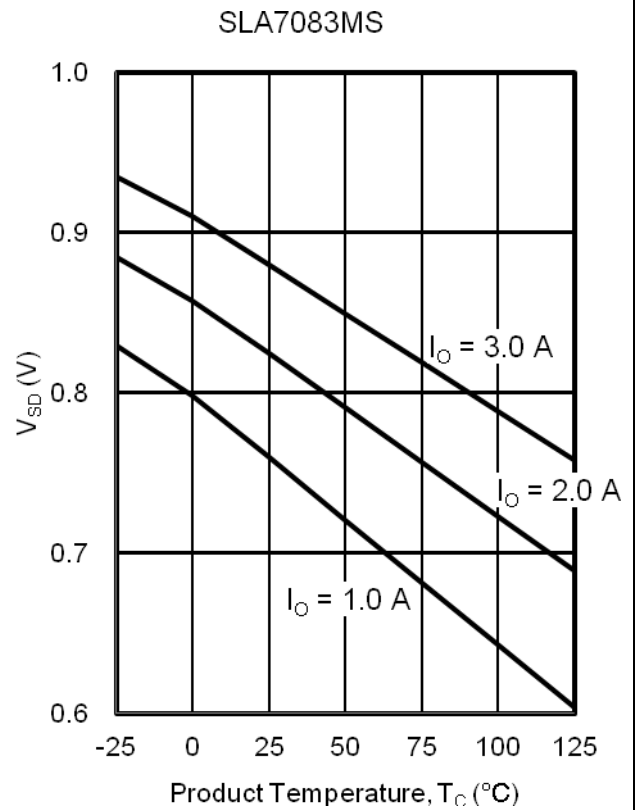
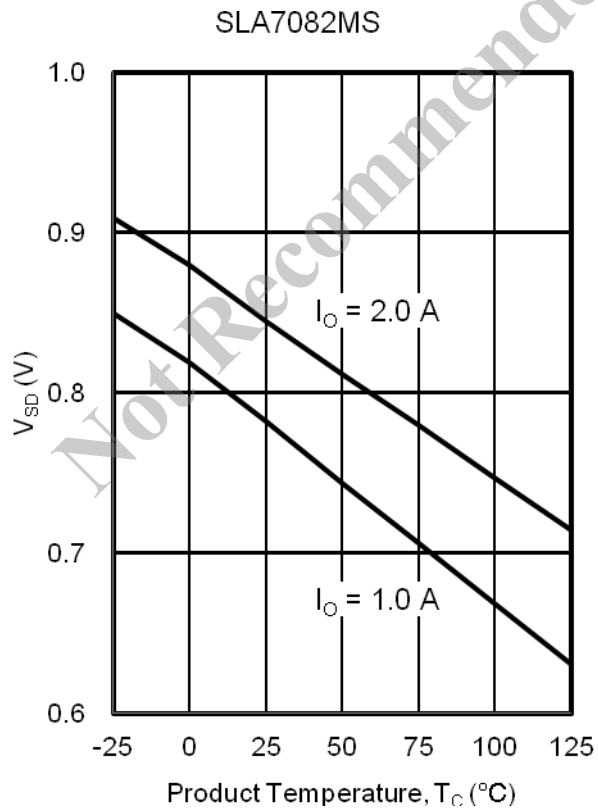
- With no external heatsink connection: 90 °C
- With external heatsink connection: 80 °C

14. Characteristics Data

(1) Output MOSFET On-Voltage, $V_{DS(on)}$



(2) Output MOSFET Body Diodes Forward Voltage, V_F



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